



## Material Content Data Sheet



Sales Product Name	BTS50015-1TAA			Issued		29. August 2013		
MA#	MA001052938							
Package	PG-TO263-7-8			Weight*		1521.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.102	0.86	0.86	8611	8611
leadframe	non noble metal	iron	7439-89-6	0.905	0.06		594	
	inorganic material	phosphorus	7723-14-0	0.271	0.02		178	
	non noble metal	copper	7440-50-8	903.346	59.36	59.44	593720	594492
wire	non noble metal	aluminium	7429-90-5	10.925	0.72	0.72	7180	7180
encapsulation	organic material	carbon black	1333-86-4	8.630	0.57		5672	
	plastics	epoxy resin	-	94.935	6.24		62395	
	inorganic material	silicondioxide	60676-86-0	471.796	31.01	37.82	310086	378153
leadfinish	non noble metal	tin	7440-31-5	8.717	0.57	0.57	5729	5729
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.244	0.21	0.21	2132	2137
glue	plastics	Polyimide	26023-21-2	0.128	0.01	0.01	84	84
solder	noble metal	silver	7440-22-4	0.137	0.01		90	
	non noble metal	tin	7440-31-5	0.110	0.01		72	
	non noble metal	lead	7439-92-1	5.252	0.35	0.37	3452	3614
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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